

A M E N D M E N T S T O T H E C L A I M S

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) An apparatus, comprising:

a first printed circuit board ~~portion including a lower quality dielectric material~~; and

a second printed circuit board ~~portion coupled to the first portion, the second portion including a higher quality dielectric material~~;

a first integrated circuit device having a first set of signal contacts attached to a first area of the first board via solderjoint interfaces and a second set of signal contacts attached to a first area of the second board via solderjoint interfaces; and

a second integrated circuit device having a first set of signal contacts attached to a second area of the first board, remote from the first area of the first board, via a solderjoint interface and a second set of signal contacts attached to a second area of the second board, remote from the second area of the first board, via solderjoint interfaces;

wherein the second board is integrated into the solderjoint interfaces between (i) the first and second integrated circuit devices and (ii) the first printed circuit board.

2. (currently amended) The apparatus of claim 1, wherein the first board is made of a first material and the second board is made of a second material, and the second material is substantially more dielectric than the first material ~~second portion is integrated into a solderjoint interface area between a device and the first portion~~.

3. (currently amended) The apparatus of claim 1, wherein the second printed circuit board comprises a polyimide film further including:

~~a device electrically coupled to the second portion via a solderjoint interface.~~

4. (currently amended) The apparatus of claim [[3]] 1 , wherein at least one of the integrated circuit devices device comprises at least one of: (i) a socket, (ii) a package, (iii) a chip-set, (iv) a processor, (v) a peripheral interface, or and (vi) an input output device.

5-10. canceled.

11. (currently amended) The apparatus of claim 1, wherein the first board is made of a first material and the second board is made of a second material, and the second material is substantially more homogeneous than the first material the higher-quality dielectric material is more homogeneous as compared to the lower-quality dielectric material .

12. (currently amended) The apparatus of claim 1, wherein the second board portion is thinner as compared to than the first board portion.

13. (currently amended) A method, comprising:

forming traces on a first printed circuit board portion that includes a lower-quality dielectric material ; and

forming traces on a second printed circuit board portion coupled to the first portion, the second portion including a higher-quality dielectric material ;

mounting a first integrated circuit device such that a first set of signal contacts are attached to a first area of the first board via solderjoint interfaces and a second set of signal contacts are attached to a first area of the second board via solderjoint interfaces; and

mounting a second integrated circuit device such that a first set of signal contacts are attached to a second area of the first board, remote from the first area of the first board, via a solderjoint interface and a second set of signal contacts are attached to a second area of the second board, remote from the second area of the first board, via solderjoint interfaces;

wherein the second board is integrated into the solderjoint interfaces between (i) the first and second integrated circuit devices and (ii) the first printed circuit board .

14. (currently amended) The method of claim 13, wherein the first board is made of a first material and the second board is made of a second material, and the second material is substantially more dielectric than the first material ~~the second portion is integrated into a solderjoint interface area between a device and the first portion~~ .

15. (currently amended) A method, comprising:

providing signals through traces on a first printed circuit board portion that includes a lower-quality dielectric material ; and

providing signals through traces on a second printed circuit from a first integrated circuit device to a second integrated circuit device ~~board portion coupled to the first portion, the second portion including a higher-quality dielectric material~~

wherein the first integrated circuit device has a first set of signal contacts attached to a first area of the first board via solderjoint interfaces and a second set of signal contacts attached to a first area of the second board via solderjoint interfaces,

wherein a second integrated circuit device has a first set of signal contacts attached to a second area of the first board, remote from the first area of the first board, via a solderjoint interface and a second set of signal contacts attached to a second area of the second board, remote from the second area of the first board, via solderjoint interfaces, and

wherein the second board is integrated into the solderjoint interfaces between (i) the first and second integrated circuit devices and (ii) the first printed circuit board .

16. (currently amended) The method of claim 15, wherein the first board is made of a first material and the second board is made of a second material, and the second material is more

~~dielectric than the first material the second portion is integrated into a solderjoint interface area between a device and the first portion .~~

17-18. canceled.

19. (currently amended) A system, comprising:

a power supply to receive alternating current power and to provide direct current power;
~~and~~

~~a printed circuit board to receive the direct current power from the power supply and including:~~

~~a first printed circuit board ; portion including a lower quality dielectric material, and~~

~~a second printed circuit board ; portion coupled to the first portion, the second portion including a higher quality dielectric material~~

a first integrated circuit device having a first set of signal contacts attached to a first area of the first board via solderjoint interfaces and a second set of signal contacts attached to a first area of the second board via solderjoint interfaces; and

a second integrated circuit device having a first set of signal contacts attached to a second area of the first board, remote from the first area of the first board, via a solderjoint interface and a second set of signal contacts attached to a second area of the second board, remote from the second area of the first board, via solderjoint interfaces;

wherein the second board is integrated into the solderjoint interfaces between (i) the first and second integrated circuit devices and (ii) the first printed circuit board .

20. (currently amended) The system of claim 19, wherein ~~the first board is made of a first material and the second board is made of a second material, and the second material is substantially more dielectric than the first material the second portion is integrated into a solderjoint interface area between a processor and the first portion .~~